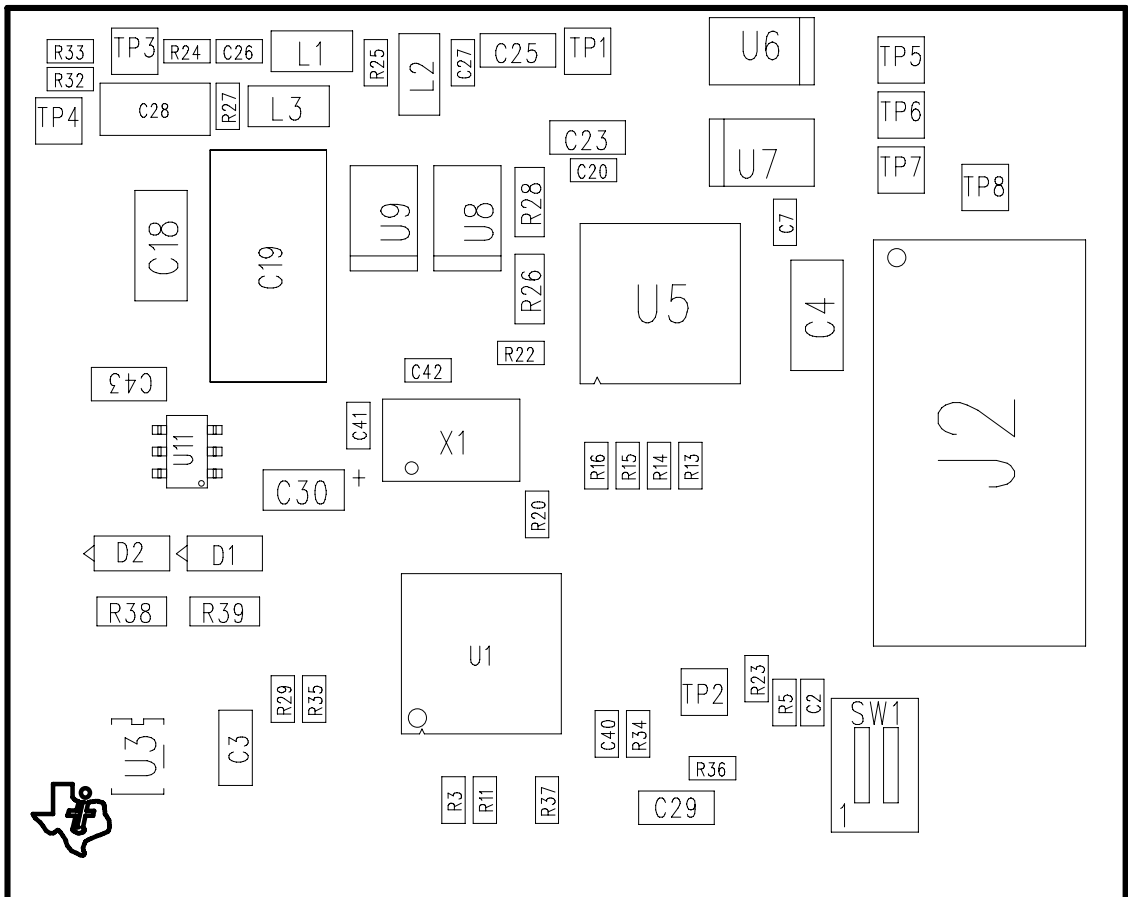


Notes:

- 1) Refer to BOM for stuffing options.
- 2) Observe polarity on diodes and capacitors.

REVISIONS				
REV.	REV.	DESCRIPTION	DATE	APPROVED



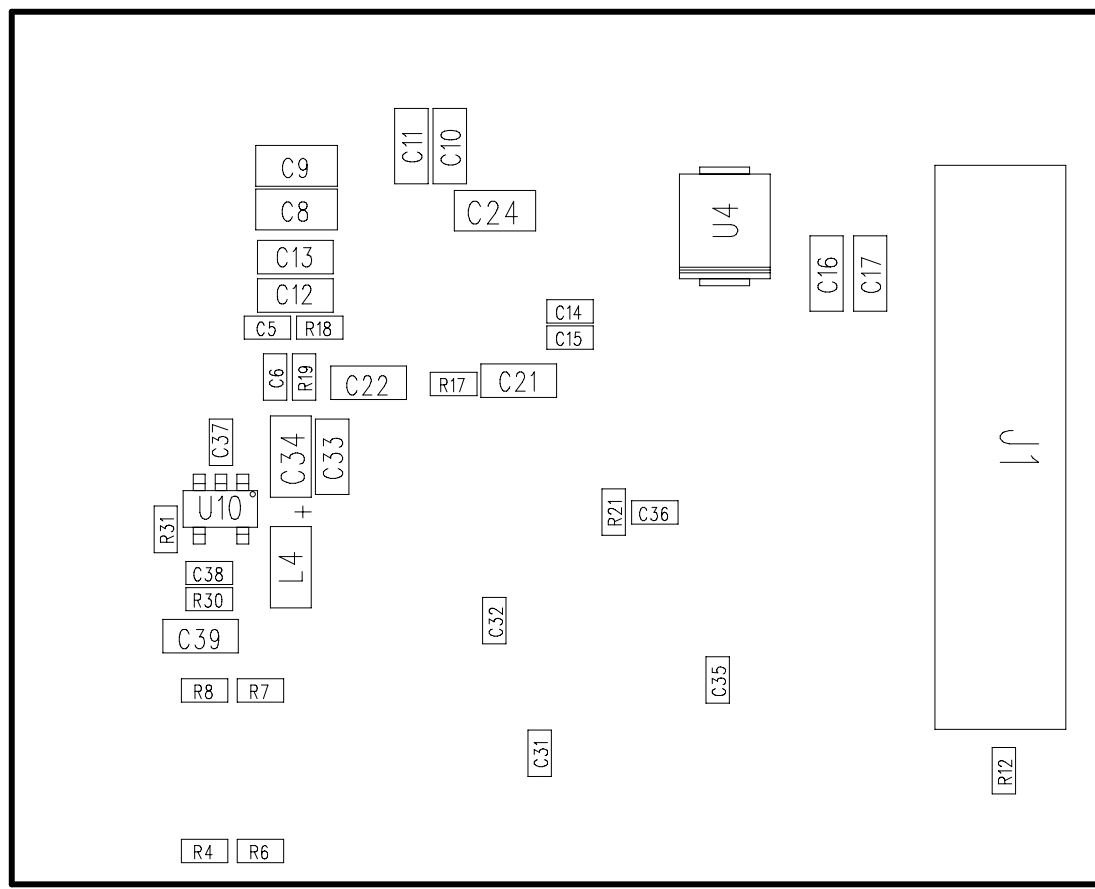
PRIMARY SIDE

APPLICATION		CONTRACT NO.	DWN: www.WSTSCORP.com	8/14	Texas Instruments, Inc.	
USED ON	NEXT ASSY.	UNLESS OTHERWISE SPECIFIED	CHK:		TITLE: ASSEMBLY DRAWING, <b>TIDM-SOMPLC-INDUSTRIAL-CENELEC</b>	
			P.E.:			
			1. TOLERANCES: LINEAR = : 0.26 (.010) ANGULAR = : 0.50°	DES.ENG.:		
MATERIAL: SEE NOTE FINISH: SEE NOTE		2. ALL DIMENSIONS ARE IN MM (INCHES).	P.C.:		SIZE	CAGE CODE NO.
DO NOT SCALE DRAWING		3. INTERPRET DRAWING IN ACCORDANCE WITH DOD-STD-100.	Q.C.:		C	
			C.M.:		DRAWING NO. PICCOLOBSOM	
			REL:		SCALE: 1:1	REV: 4
			MFG:		SHEET 1 OF 2	
			ENG.MGR:			
			OTHER:			
			OTHER:			
			OTHER:			

Notes:

- 1) Refer to BOM for stuffing options.
- 2) Observe polarity on diodes and capacitors.

REVISIONS				
REV.	REV.	DESCRIPTION	DATE	APPROVED



SECONDARY SIDE

APPLICATION		CONTRACT NO.	DWN: www.WTSCORP.com	8/14	Texas Instruments, Inc.	
USED ON	NEXT ASSY.	UNLESS OTHERWISE SPECIFIED	CHK:		TITLE: ASSEMBLY DRAWING, <b>TIDM-SOMPLC-INDUSTRIAL-CENELEC</b>	
			P.E.:			
			1. TOLERANCES: LINEAR = : 0.26 (.010) ANGULAR = : 0.50°	DES.ENG.:		DRAWING NO. PICCOLOBSOM
		2. ALL DIMENSIONS ARE IN MM (INCHES).	P.C.:			
MATERIAL: SEE NOTE FINISH: SEE NOTE		3. INTERPRET DRAWING IN ACCORDANCE WITH DOD-STD-100.	Q.C.:		SIZE C	CAGE CODE NO.
DO NOT SCALE DRAWING			C.M.:		SCALE: 1:1	
			REL:		SHEET 2 OF 2	
			MFG:			
			ENG.MGR:			
			OTHER:			
			OTHER:			
			OTHER:			

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